

**4-PIN SOP, 0.6  $\Omega$  LOW ON-STATE RESISTANCE  
600 mA CONTINUOUS LOAD CURRENT  
1-ch Optical Coupled MOS FET****DESCRIPTION**

The PS7206-1A is a low on-state resistance solid state relay containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

It is suitable for PLC, etc. because of its large continuous load current and low on-state resistance.

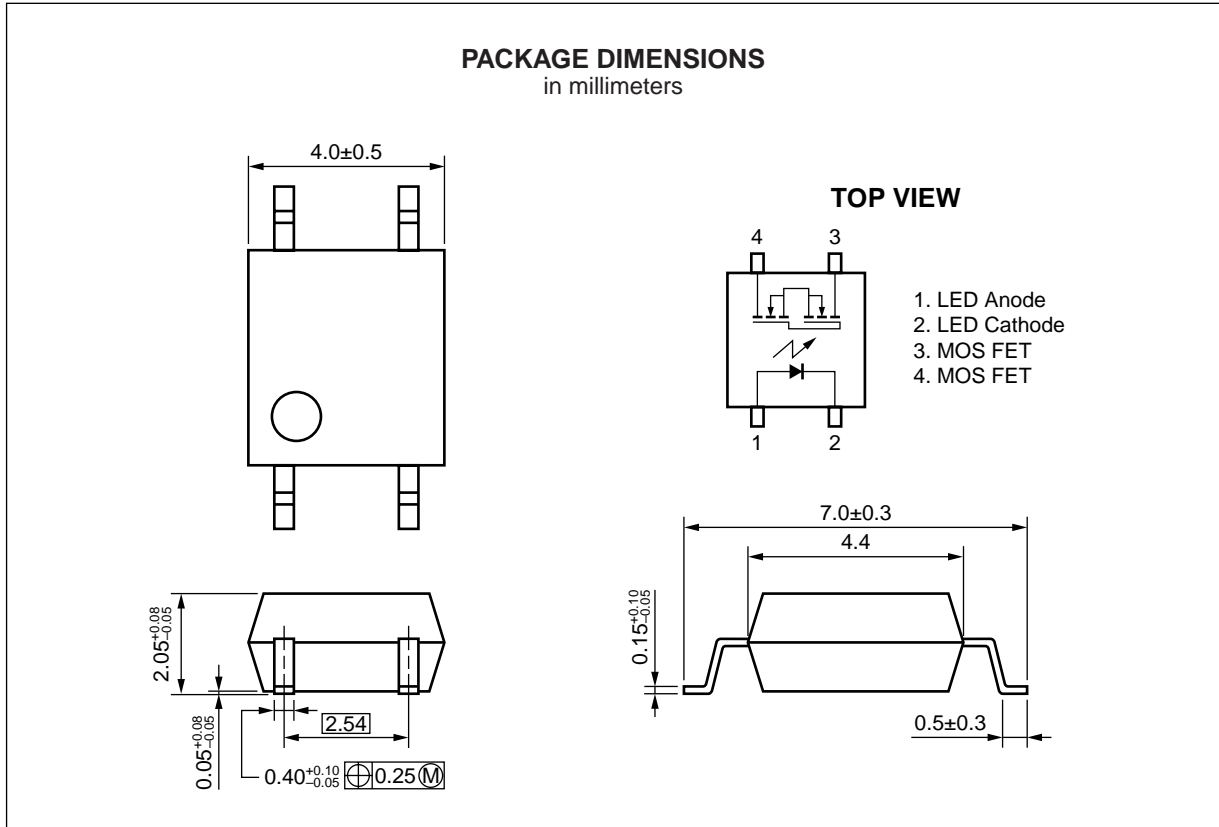
**FEATURES**

- Low on-state resistance ( $R_{on} = 0.6 \Omega$  TYP.)
- Large continuous load current ( $I_L = 600$  mA)
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage ( $BV = 1\ 500$  Vr.m.s.)
- Low offset voltage
- Ordering number of taping product: PS7206-1A-E3, E4, F3, F4

**APPLICATIONS**

- Measurement equipment
- FA equipment

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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.



★ ORDERING INFORMATION

Part Number	Package	Packing Style	Application Part Number <sup>*1</sup>
PS7200B-1A	4-pin SOP	Magazine case 100 pcs	PS7200B-1A
PS7200B-1A-E3		Embossed Tape 900 pcs/reel	
PS7200B-1A-E4			
PS7200B-1A-F3		Embossed Tape 3 500 pcs/reel	
PS7200B-1A-F4			

\*1 For the application of the Safety Standard, following part number should be used.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	I <sub>F</sub>	50	mA
	Reverse Voltage	V <sub>R</sub>	5.0	V
	Power Dissipation	P <sub>D</sub>	50	mW
	Peak Forward Current <sup>*1</sup>	I <sub>FP</sub>	1	A
MOS FET	Break Down Voltage	V <sub>L</sub>	60	V
	Continuous Load Current	I <sub>L</sub>	600	mA
	Pulse Load Current <sup>*2</sup> (AC/DC Connection)	I <sub>LP</sub>	1.2	A
	Power Dissipation	P <sub>D</sub>	300	mW
Isolation Voltage <sup>*3</sup>		BV	1 500	Vr.m.s.
Total Power Dissipation		P <sub>T</sub>	350	mW
Operating Ambient Temperature		T <sub>A</sub>	-40 to +85	°C
Storage Temperature		T <sub>stg</sub>	-40 to +100	°C

\*1 PW = 100 μs, Duty Cycle = 1 %

\*2 PW = 100 ms, 1 shot

\*3 AC voltage for 1 minute at T<sub>A</sub> = 25 °C, RH = 60 % between input and output

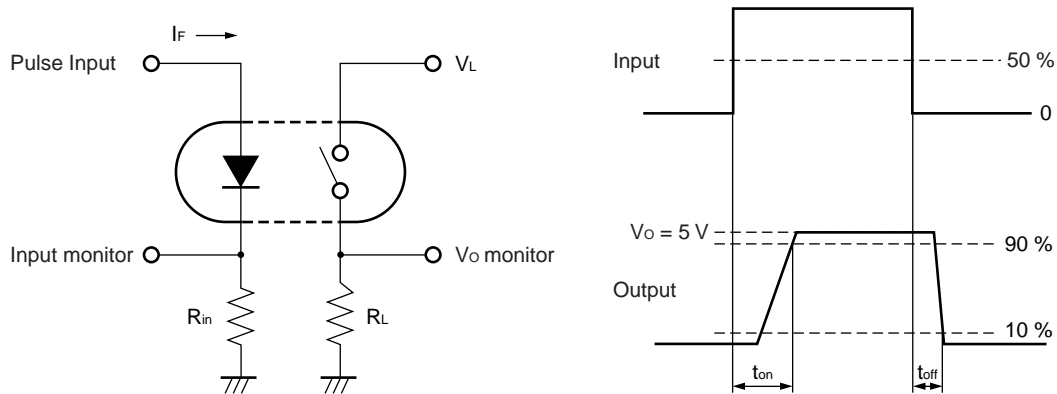
**RECOMMENDED OPERATING CONDITIONS (T<sub>A</sub> = 25 °C)**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	I <sub>F</sub>	2	10	20	mA
LED Off Voltage	V <sub>F</sub>	0		0.5	V

★ **ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)**

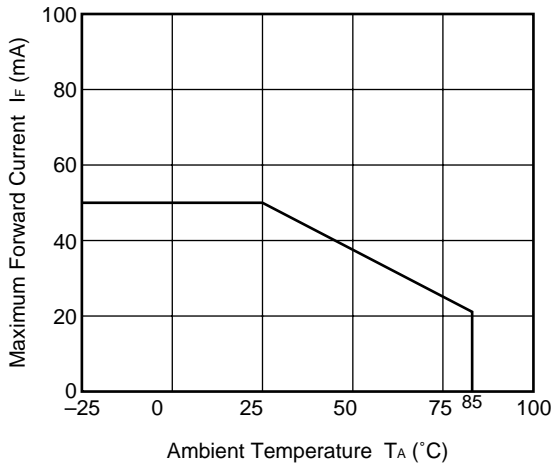
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 10 mA		1.2	1.4	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	I <sub>Loff</sub>	V <sub>D</sub> = 60 V			1.0	μA
	Output Capacitance	C <sub>out</sub>	V <sub>D</sub> = 0 V, f = 1 MHz		70		pF
Coupled	LED On-state Current	I <sub>Fon</sub>	I <sub>L</sub> = 600 mA			2.0	mA
	On-state Resistance	R <sub>on</sub>	I <sub>F</sub> = 10 mA, I <sub>L</sub> = 600 mA, t ≤ 10 ms		0.6	0.8	Ω
	Turn-on Time	t <sub>on</sub>	I <sub>F</sub> = 10 mA, V <sub>O</sub> = 5 V, R <sub>L</sub> = 500 Ω, PW ≥ 10 ms		0.4	2.0	ms
	Turn-off Time	t <sub>off</sub>			0.08	0.5	
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1.0 kV <sub>bc</sub>	10 <sup>9</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.5		pF

\*1 Test Circuit for Switching Time

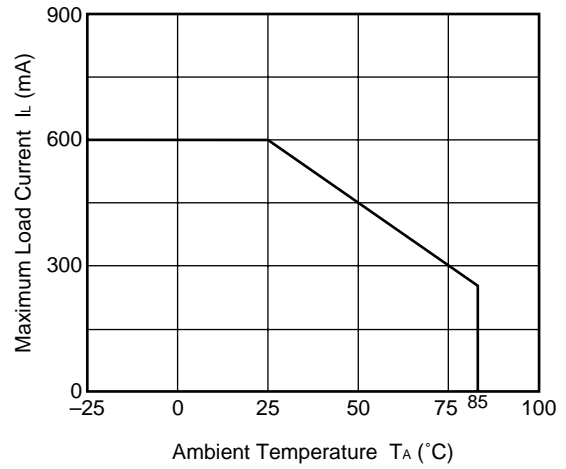


★ TYPICAL CHARACTERISTICS ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

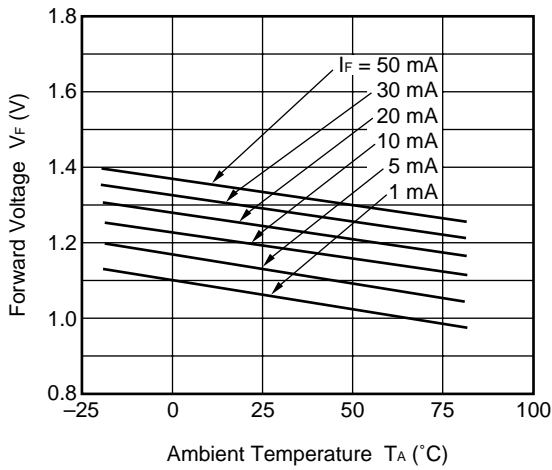
MAXIMUM FORWARD CURRENT vs. AMBIENT TEMPERATURE



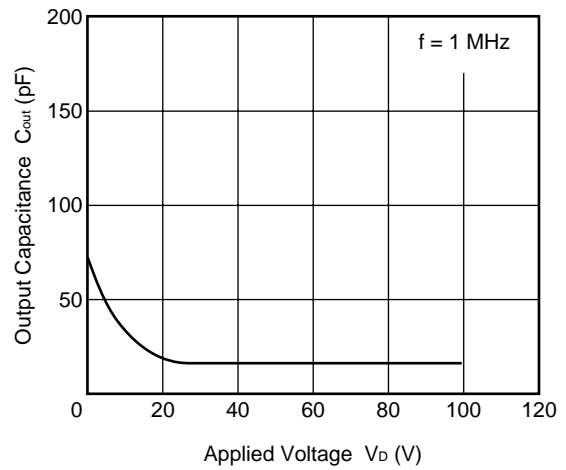
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



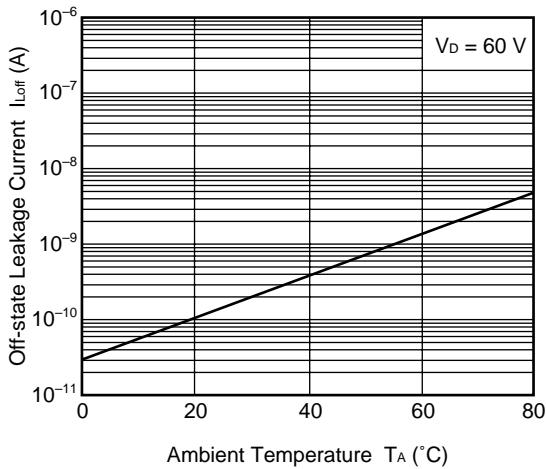
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



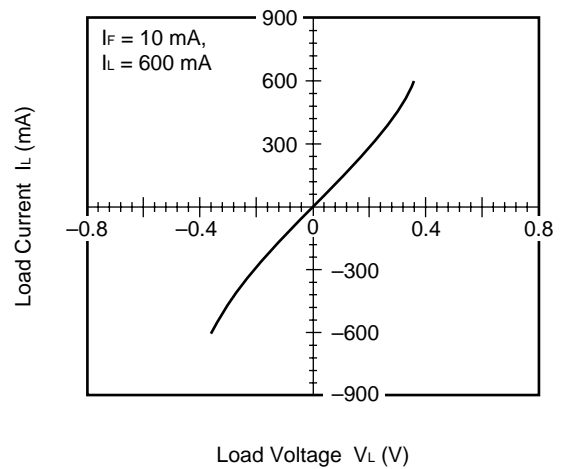
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



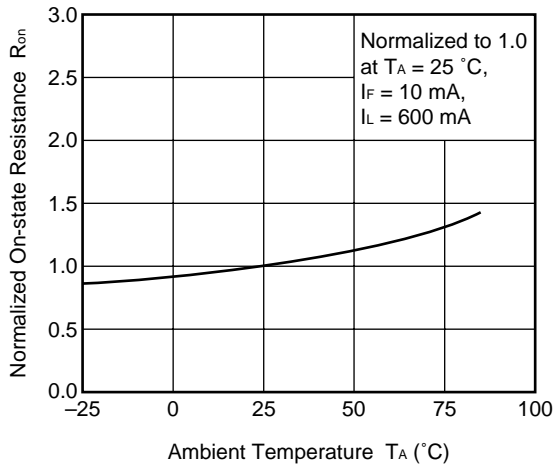
OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE



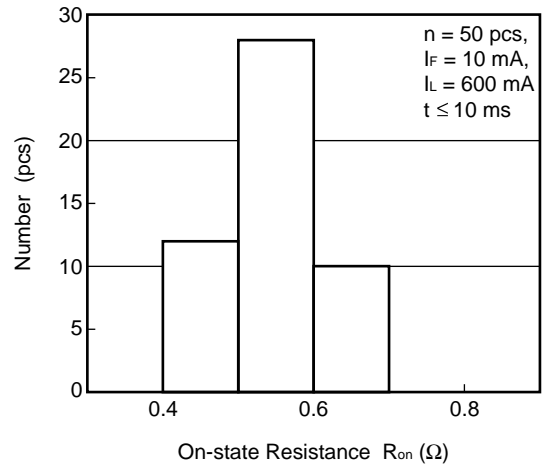
LOAD CURRENT vs. LOAD VOLTAGE



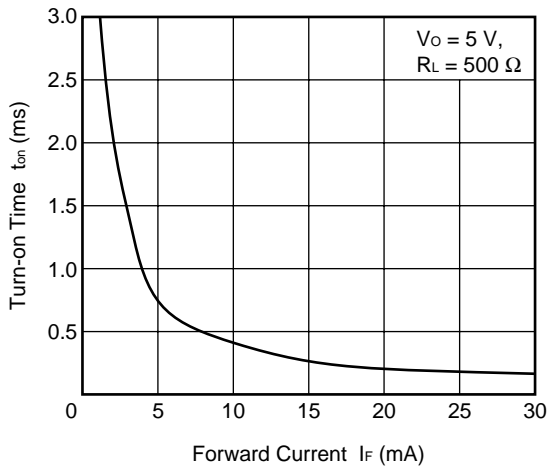
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



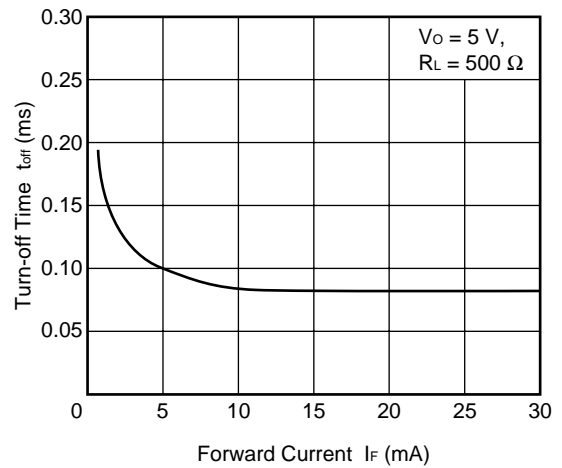
ON-STATE RESISTANCE DISTRIBUTION



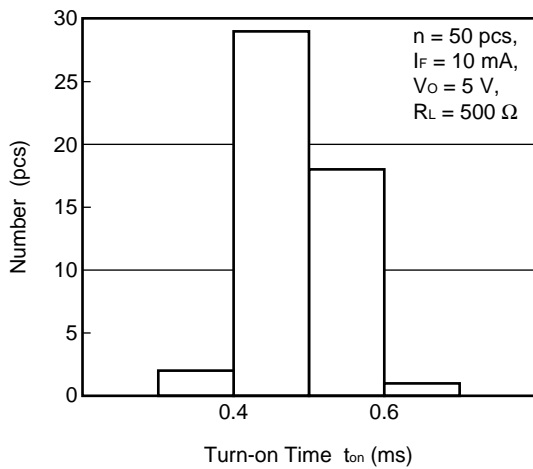
TURN-ON TIME vs. FORWARD CURRENT



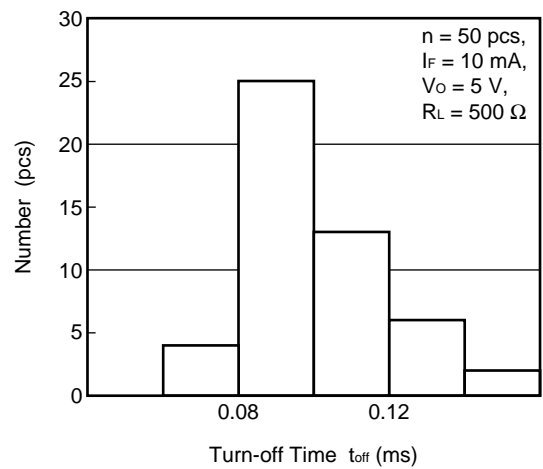
TURN-OFF TIME vs. FORWARD CURRENT



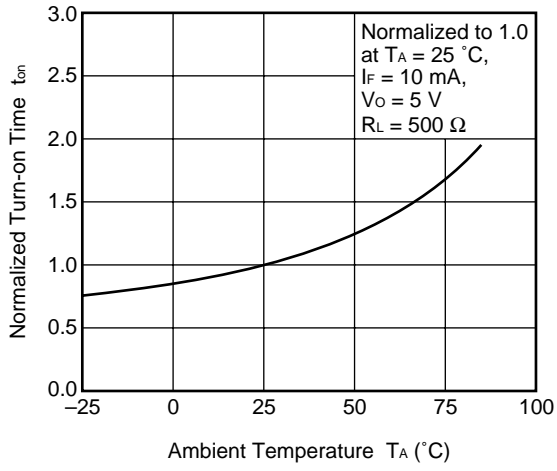
TURN-ON TIME DISTRIBUTION



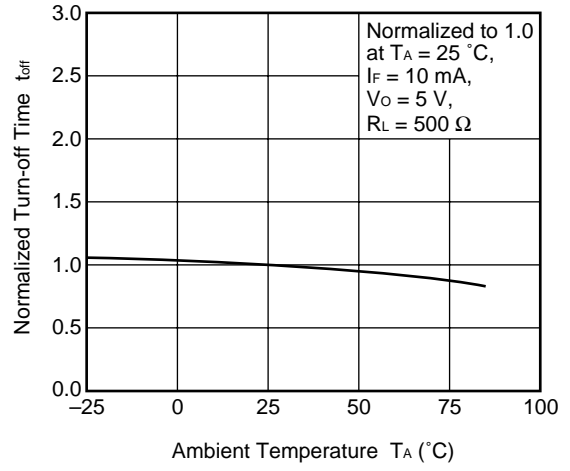
TURN-OFF TIME DISTRIBUTION



NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE



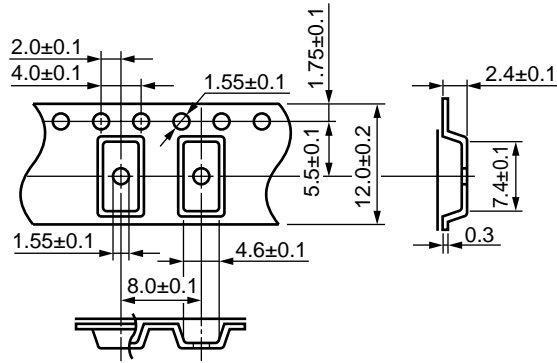
NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



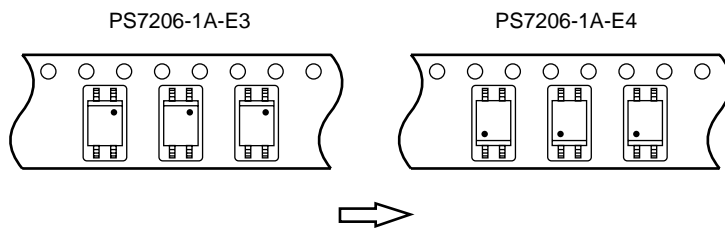
**Remark** The graphs indicate nominal characteristics.

★ TAPING SPECIFICATIONS (in millimeters)

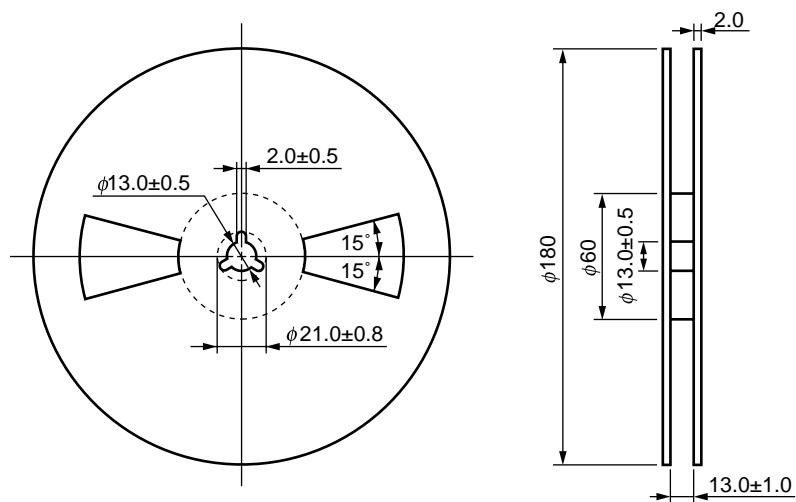
Outline and Dimensions (Tape)



Tape Direction



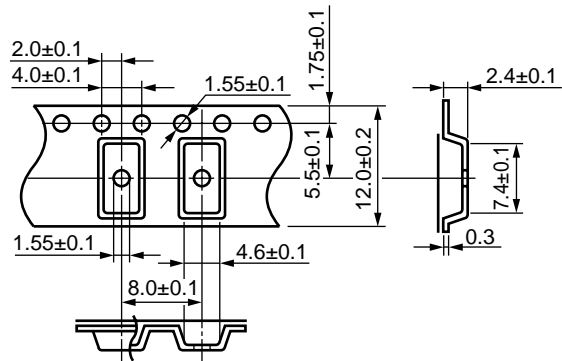
Outline and Dimensions (Reel)



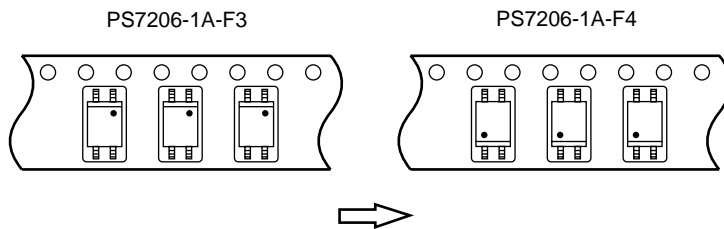
Packing: 900 pcs/reel



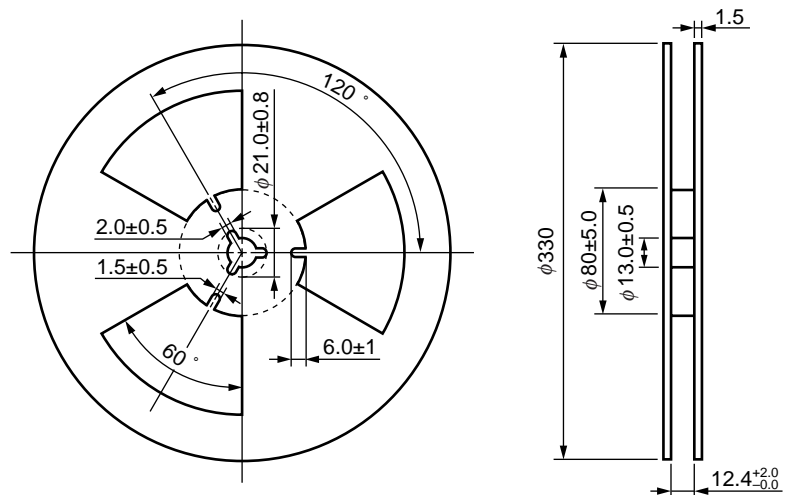
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



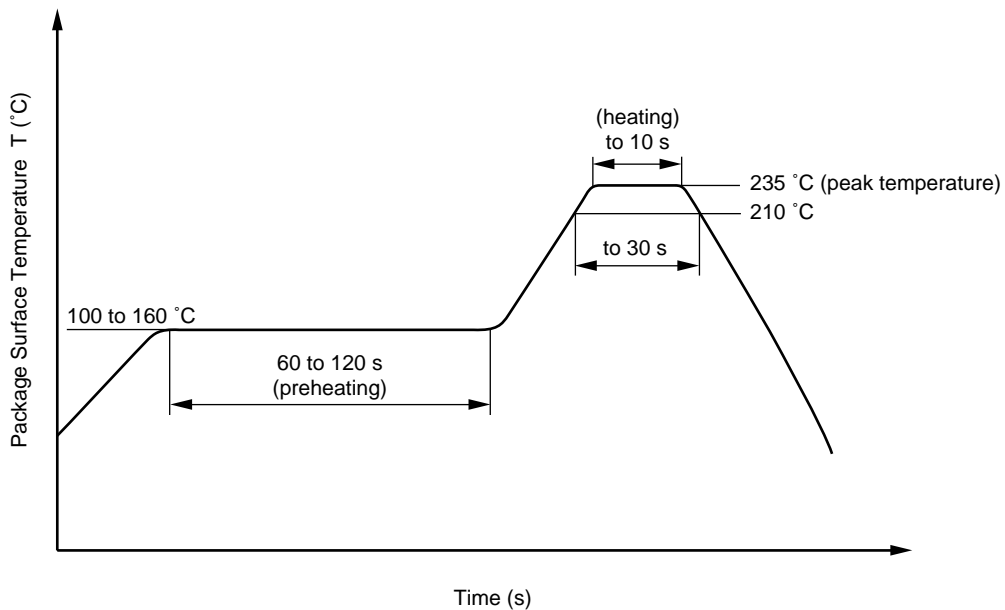
Packing: 3 500 pcs/reel

★ **RECOMMENDED SOLDERING CONDITIONS**

**(1) Infrared reflow soldering**

- Peak reflow temperature 235 °C or below (package surface temperature)
- Time of temperature higher than 210 °C 30 seconds or less
- Number of reflows Two
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

Recommended Temperature Profile of Infrared Reflow



**(2) Dip soldering**

- Temperature 260 °C or below (molten solder temperature)
- Time 10 seconds or less
- Number of times One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt % is recommended.)

**(3) Cautions**

- Fluxes  
Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

[MEMO]

## CAUTION

**Within this device there exists GaAs (Gallium Arsenide) material which is a harmful substance if ingested. Please do not under any circumstances break the hermetic seal.**

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